

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-14. (Canceled).

15. (Currently Amended) The housing as recited in claim ~~[[14]]~~ 18, wherein the floor plate, the cover and the electrical conductors are made of the same material.

16. (Previously Presented) The housing as recited in claim 15, wherein the floor plate and the cover are made of aluminum.

17. (Previously Presented) The housing as recited in Claim 15, wherein the electrical conductors are made of a copper-containing material.

18. (Currently Amended) A ~~[[The]]~~ housing as recited in Claim 14 for an electronic circuit having a plurality of electrical contacts leading to the outside of the housing via individual electrical conductors, comprising:

a floor plate;

a cover;

a seal between the floor plate and the cover;

wherein:

the seal is configured as a single part for sealing a gap between the floor plate and the cover;

the electrical conductors are led in a frame and are positioned fixedly with respect to one another, the frame being situated between the floor plate and the cover; ~~[[,]]~~ and ~~wherein~~

the frame defines at least one of relative positions and relative clearances of the floor plate, the cover and the electrical conductors with respect to one another in the housing.

19. (Previously Presented) The housing as recited in claim 18, wherein at least one of the floor plate, the cover and the frame has at least one of a spacer and a stop, and wherein the at least one of the spacer and the stop is positioned to maintain a predetermined clearance of the electrical conductors from one of the floor plate and the cover when the housing is closed.

20. (Previously Presented) The housing as recited in claim 18, wherein the floor plate has a depression for accommodating a part of the seal.

21. (Previously Presented) The housing as recited in claim 18, wherein the frame has a recess, and wherein the recess, together with the floor plate, at least partially borders the gap.

22. (Currently Amended) The housing as recited in claim ~~[[14]]~~ 18, wherein the electrical conductors are configured as a pressed screen strip.

23. (Canceled).

24. (Currently Amended) A ~~[[The]]~~ method as recited in claim 23 for sealing a housing for an electronic circuit having a plurality of electrical contacts leading to the outside of the housing via individual electrical conductors, and the housing including a floor plate, a cover and a seal between the floor plate and the cover, the method comprising:

providing the seal in a single-part form in a gap between the floor plate and the cover;
wherein:

the electrical conductors are led through the seal; and

the providing of the seal takes place during the assembly of the housing and includes the following steps:

applying a first sealing compound bed to a surface of the floor plate in the surroundings of the electronic circuit on the floor plate;

putting a frame having the electrical conductors onto the first sealing compound bed, whereby a part of the first sealing compound bed wells up between the electrical conductors;

applying a second sealing compound bed to a clearance space above the electrical conductors; and

inserting the cover of the housing into the second sealing compound bed.

25. (Previously Presented) The method as recited in Claim 24, wherein the cover of the housing is inserted into the second sealing compound bed only after the electrical conductors have been bonded to the electronic circuit.

26. (Currently Amended) A [[The]] method as recited in claim 23 for sealing a housing for an electronic circuit having a plurality of electrical contacts leading to the outside of the housing via individual electrical conductors, and the housing including a floor plate, a cover and a seal between the floor plate and the cover, the method comprising:

providing the seal in a single-part form in a gap between the floor plate and the cover;
wherein;

the electrical conductors are led through the seal; and

the providing of the seal takes place during the assembly of the housing and includes the following steps:

applying a frame to the floor plate at a predetermined position, wherein the electrical conductors are led through the frame and are fixedly positioned within the frame with respect to one another, and bonding the electrical conductors to the electronic circuit, wherein the frame has at least one of spacers and stops;

filling fluid sealing compound into a groove defined by the surface of the floor plate and a recess in the frame; and

closing the housing by positioning the cover on the at least one of the spacers and stops of the frame, wherein the edge of the cover penetrates into the fluid sealing compound in the groove.